

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Appl. No.** : TBA  
**Applicant(s)** : Edward G. Combs *et al.*  
**Filed** : March 18, 2004  
**TC/A.U.** : TBA  
**Examiner** : TBA  
**Docket No.** : 36080-00802  
**Customer No.** : 27171  
**Title** : *Method of Manufacturing an Enhanced Thermal Dissipation Integrated Circuit Package* (as amended)

**COMMISSIONER FOR PATENTS**  
**P.O. Box 1450**  
**Alexandria, VA 22313-1450**

**PRELIMINARY AMENDMENT**

Sir:

Prior to examination, please amend the above-referenced application as follows:

**Amendments to the Title** begin on page 2 of this paper.

**Amendments to the Abstract** begin on page 3 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 4 of this paper.

**Remarks** begin on page 8 of this paper.

IN THE TITLE

Please replace the Title with the following:

***Method of Manufacturing an Enhanced Thermal Dissipation Integrated Circuit Package***